

The SN54125, SN54126, SN74125, SN74126, and SN54LS126A are obsolete and are no longer supplied.

SN54125, SN54126, SN54LS125A, SN54LS126A, SN74125, SN74126, SN74LS125A, SN74LS126A QUADRUPLE BUS BUFFERS WITH 3-STATE OUTPUTS

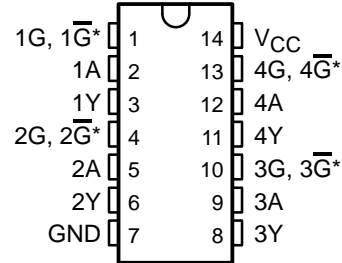
SDLS044A – DECEMBER 1983 – REVISED MARCH 2002

- Quad Bus Buffers
- 3-State Outputs
- Separate Control for Each Channel

description

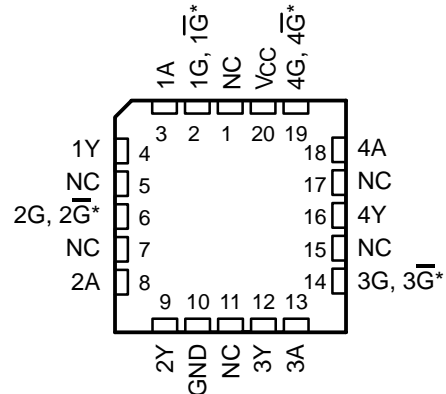
These bus buffers feature three-state outputs that, when enabled, have the low impedance characteristics of a TTL output with additional drive capability at high logic levels to permit driving heavily loaded bus lines without external pullup resistors. When disabled, both output transistors are turned off, presenting a high-impedance state to the bus so the output will act neither as a significant load nor as a driver. The '125 and 'LS125A devices' outputs are disabled when \bar{G} is high. The '126 and 'LS126A devices' outputs are disabled when G is low.

SN54125, SN54126, SN54LS125A,
SN54LS126A . . . J OR W PACKAGE
SN74125, SN74126 . . . N PACKAGE
SN74LS125A, SN74LS126A . . . D, N, OR NS PACKAGE
(TOP VIEW)



\bar{G} on '125 and 'LS125A devices;
G on 126 and 'LS126A devices

SN54LS125A, SN54LS126A . . . FK PACKAGE
(TOP VIEW)



\bar{G} on '125 and 'LS125A devices;
G on 126 and 'LS126A devices
NC – No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2002, Texas Instruments Incorporated
On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

**SN54125, SN54126, SN54LS125A, SN54LS126A,
SN74125, SN74126, SN74LS125A, SN74LS126A
QUADRUPLE BUS BUFFERS WITH 3-STATE OUTPUTS**

SDLS044A – DECEMBER 1983 – REVISED MARCH 2002

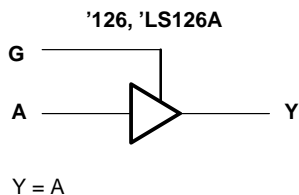
The SN54125, SN54126, SN74125,
SN74126, and SN54LS126A are
obsolete and are no longer supplied.

ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – N	Tube	SN74LS125AN	SN74LS125AN
		Tube	SN74LS126AN	SN74LS126AN
	SOIC – D	Tube	SN74LS125AD	LS125A
		Tape and reel	SN74LS125ADR	
		Tube	SN74LS126AD	LS126A
		Tape and reel	SN74LS126ADR	
	SOP – NS	Tape and reel	SN74LS125ANSR	74LS125A
Tape and reel		SN74LS126ANSR	74LS126A	
–55°C to 125°C	CDIP – J	Tube	SN54LS125AJ	SN54LS125AJ
		Tube	SNJ54LS125AJ	SNJ54LS125AJ
	CFP – W	Tube	SNJ54LS125AW	SNJ54LS125AW
	LCCC – FK	Tube	SNJ54LS125AFK	SNJ54LS125AFK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

logic diagram (each gate)



**SN54125, SN54126, SN54LS125A, SN54LS126A,
SN74125, SN74126, SN74LS125A, SN74LS126A
QUADRUPLE BUS BUFFERS WITH 3-STATE OUTPUTS**

The SN54125, SN54126, SN74125, SN74126, and SN54LS126A are obsolete and are no longer supplied.

SDLS044A – DECEMBER 1983 – REVISED MARCH 2002

schematics (each gate)



absolute maximum ratings over operating free-air temperature (unless otherwise noted)†
(**'125 and '126**)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage, V_I	5.5 V
Package thermal impedance, θ_{JA} (see Note 2): N package	80°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

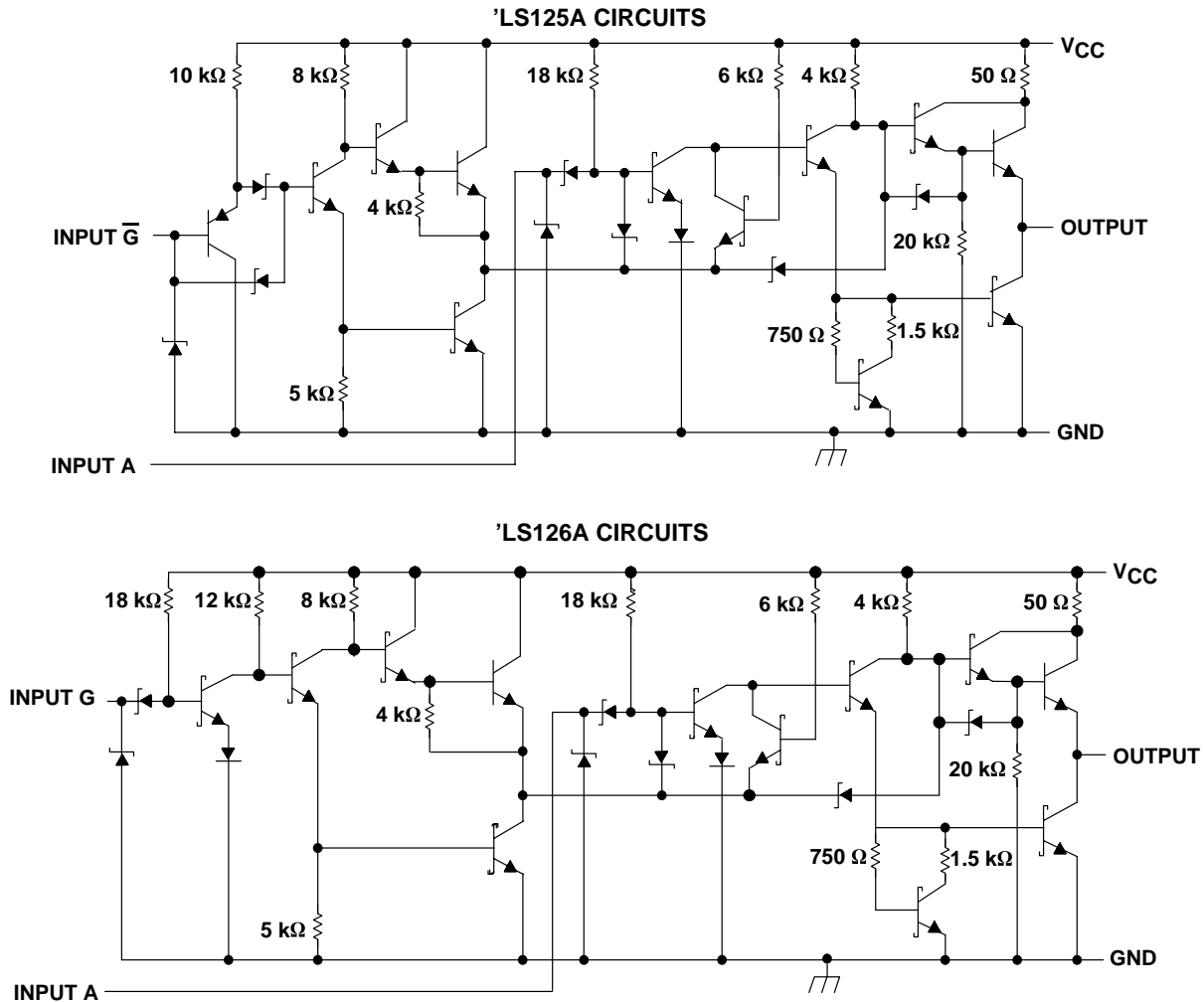
- NOTES: 1. Voltage values are with respect to network ground terminal.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

**SN54125, SN54126, SN54LS125A, SN54LS126A,
SN74125, SN74126, SN74LS125A, SN74LS126A
QUADRUPLE BUS BUFFERS WITH 3-STATE OUTPUTS**

SDLS044A – DECEMBER 1983 – REVISED MARCH 2002

The SN54125, SN54126, SN74125, SN74126, and SN54LS126A are obsolete and are no longer supplied.

schematics (each gate)



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature (unless otherwise noted)†
('LS125A and 'LS126A)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage, V_I	7 V
Package thermal impedance, θ_{JA} (see Note 2): D package	86°C/W
N package	80°C/W
NS package	76°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. Voltage values are with respect to network ground terminal.
2. The package thermal impedance is calculated in accordance with JESD 51-7.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

The SN54125, SN54126, SN74125, SN74126, and SN54LS126A are obsolete and are no longer supplied.

SN54125, SN54126, SN54LS125A, SN54LS126A, SN74125, SN74126, SN74LS125A, SN74LS126A
QUADRUPLE BUS BUFFERS WITH 3-STATE OUTPUTS

SDLS044A - DECEMBER 1983 - REVISED MARCH 2002

recommended operating conditions

		SN54125 SN54126			SN74125 SN74126			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{IH}	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.8			0.8	V
I _{OH}	High-level output current			-2			-5.2	mA
I _{OL}	Low-level output current			16			16	mA
T _A	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†		SN54125 SN54126			SN74125 SN74126			UNIT	
			MIN	TYP‡	MAX	MIN	TYP‡	MAX		
V _{IK}	V _{CC} = MIN, I _I = -12 mA				-1.5			-1.5	V	
V _{OH}	V _{CC} = MIN, V _{IL} = 0.8 V	V _{IH} = 2 V, I _{OH} = -2 mA	2.4	3.3					V	
		V _{IH} = 2 V, I _{OH} = -5.2 mA				2.4	3.1			
V _{OL}	V _{CC} = MIN, I _{OL} = 16 mA	V _{IH} = 2 V, V _{IL} = 0.8 V			0.4			0.4	V	
I _{OZ}	V _{CC} = MAX, V _{IL} = 0.8 V	V _{IH} = 2 V, V _O = 2.4 V			40			40	μA	
		V _{IH} = 2 V, V _O = 0.4 V			-40			-40		
I _I	V _{CC} = MAX, V _I = 6.5 V				1			1	mA	
I _{IH}	V _{CC} = MAX, V _I = 2.4 V				40			40	μA	
I _{IL}	V _{CC} = MAX, V _I = 0.4 V				-1.6			-1.6	mA	
I _{OS} §	V _{CC} = MAX				-30		-70	-28	-70	mA
I _{CC}	V _{CC} = MAX (see Note 3)	'125	32	54			32	54	mA	
		'126	36	62			36	62		

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time.

NOTE 3: Data inputs = 0 V; output control = 4.5 V for '125 and 0 V for '126.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figure 1)

PARAMETER	TEST CONDITIONS		SN54125 SN74125			SN54126 SN74126			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
t _{PLH}	R _L = 400 Ω, C _L = 50 pF		8	13		8	13	ns	
t _{PHL}			12	18		12	18		
t _{PZH}	R _L = 400 Ω, C _L = 50 pF		11	17		11	18	ns	
t _{PZL}			16	25		16	25		
t _{PHZ}	R _L = 400 Ω, C _L = 5 pF		5	8		10	16	ns	
t _{PLZ}			7	12		12	18		



**SN54125, SN54126, SN54LS125A, SN54LS126A,
SN74125, SN74126, SN74LS125A, SN74LS126A
QUADRUPLE BUS BUFFERS WITH 3-STATE OUTPUTS**

SDLS044A – DECEMBER 1983 – REVISED MARCH 2002

The SN54125, SN54126, SN74125,
SN74126, and SN54LS126A are
obsolete and are no longer supplied.

recommended operating conditions

		SN54LS125A SN54LS126A			SN74LS125A SN74LS126A			UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX			
V _{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V		
V _{IH}	High-level input voltage	2			2			V		
V _{IL}	Low-level input voltage	0.7			0.8			V		
I _{OH}	High-level output current	-1			-2.6			mA		
I _{OL}	Low-level output current	12			24			mA		
T _A	Operating free-air temperature	-55			125			0	70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†		SN54LS125A SN54LS126A			SN74LS125A SN74LS126A			UNIT			
			MIN	TYP‡	MAX	MIN	TYP‡	MAX				
V _{IK}	V _{CC} = MIN, I _I = -18 mA		-1.5			-1.5			V			
V _{OH}	V _{CC} = MIN, V _{IH} = 2 V	V _{IL} = 0.7 V, I _{OH} = -1 mA	2.4						V			
		V _{IL} = 0.8 V, I _{OH} = -2.6 mA				2.4						
V _{OL}	V _{CC} = MIN, V _{IH} = 2 V	V _{IL} = 0.7 V, I _{OL} = 12 mA	0.25		0.4				V			
		V _{IL} = 0.8 V, I _{OL} = 12 mA			0.25		0.4					
		V _{IL} = 0.8 V, I _{OL} = 24 mA			0.35		0.5					
I _{OZ}	V _{CC} = MAX, V _{IH} = 2 V,	V _{IL} = 0.7 V	V _O = 2.4 V		20				µA			
			V _O = 0.4 V		-20							
		V _{IL} = 0.8 V	V _O = 2.4 V				20					
			V _O = 0.4 V				-20					
I _I	V _{CC} = MAX, V _I = 7 V		0.1			0.1			mA			
I _{IH}	V _{CC} = MAX, V _I = 2.7 V		20			20			µA			
I _{IL}	V _{CC} = MAX, V _I = 0.4 V	'LS125A-G inputs		-0.2			-0.2			mA		
		'LS125A-A inputs; 'LS126A All inputs		-0.4			-0.4					
I _{OS} §	V _{CC} = MAX		-40		-225		-40		-225		mA	
I _{CC}	V _{CC} = MAX (see Note 4)	'LS125A		11		20		11		20		mA
		'LS126A		12		22		12		22		

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

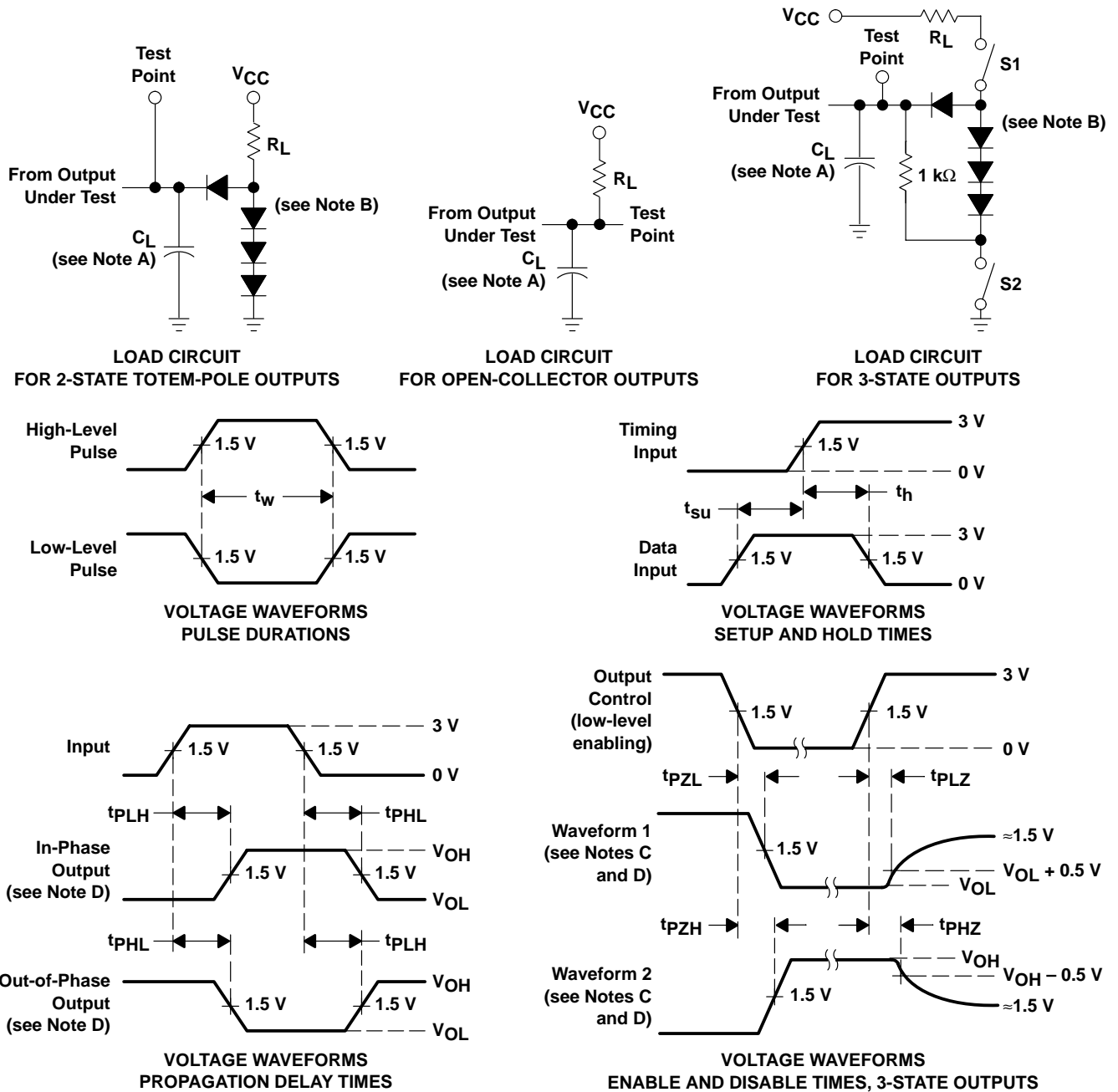
NOTE 4: Data inputs = 0 V; output control = 4.5 V for 'LS125A and 0 V for 'LS126A.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figure 1)

PARAMETER	TEST CONDITIONS		SN54LS125A SN74LS125A			SN54LS126A SN74LS126A			UNIT	
			MIN	TYP	MAX	MIN	TYP	MAX		
t _{PLH}	R _L = 667 Ω, C _L = 45 pF	9		15		9		15		ns
t _{PHL}		7		18		8		18		
t _{PZH}	R _L = 667 Ω, C _L = 45 pF	12		20		16		25		ns
t _{PZL}		15		25		21		35		
t _{PHZ}	R _L = 667 Ω, C _L = 5 pF	20						25		ns
t _{PLZ}		20						25		



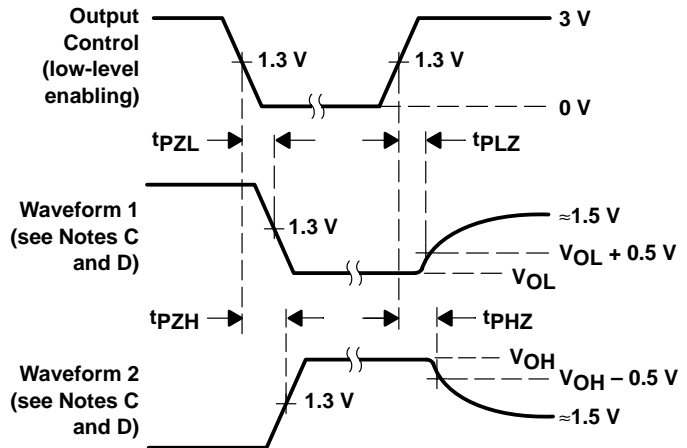
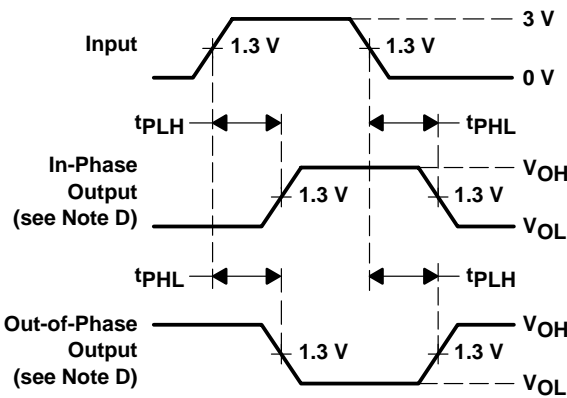
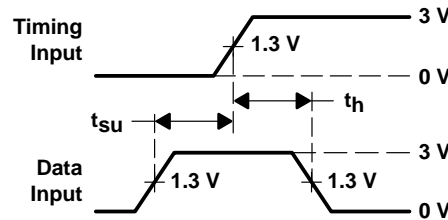
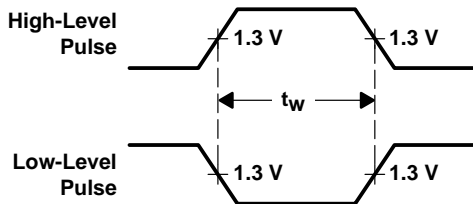
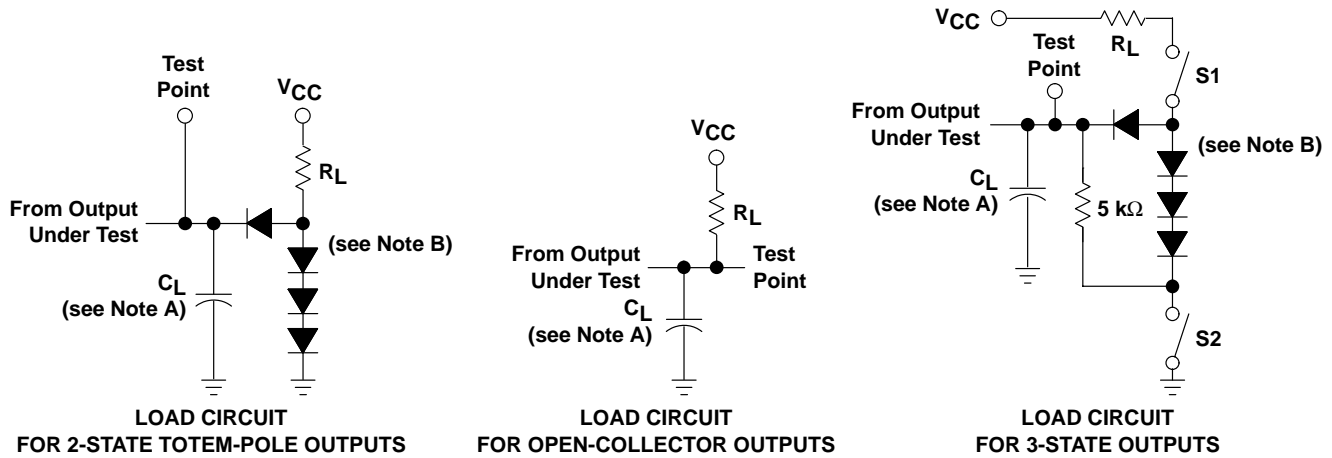
PARAMETER MEASUREMENT INFORMATION
SERIES 54/74 DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
 B. All diodes are 1N3064 or equivalent.
 C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 D. S1 and S2 are closed for t_{PLH} , t_{PHL} , t_{PHZ} , and t_{PLZ} ; S1 is open and S2 is closed for t_{PZH} ; S1 is closed and S2 is open for t_{PZL} .
 E. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O \approx 50 \Omega$; t_r and $t_f \leq 7$ ns for Series 54/74 devices and t_r and $t_f \leq 2.5$ ns for Series 54S/74S devices.
 F. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION
 SERIES 54LS/74LS DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
 B. All diodes are 1N3064 or equivalent.
 C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 D. S1 and S2 are closed for t_{PLH} , t_{PHL} , t_{PHZ} , and t_{PLZ} ; S1 is open and S2 is closed for t_{PZH} ; S1 is closed and S2 is open for t_{PZL} .
 E. Phase relationships between inputs and outputs have been chosen arbitrarily for these examples.
 F. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O \approx 50 \Omega$, $t_r \leq 1.5$ ns, $t_f \leq 2.6$ ns.
 G. The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/32301B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32301B2A	Samples
JM38510/32301BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32301BCA	Samples
JM38510/32301BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32301BDA	Samples
M38510/32301B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32301B2A	Samples
M38510/32301BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32301BCA	Samples
M38510/32301BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32301BDA	Samples
SN54LS125AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS125AJ	Samples
SN74LS125AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS125A	Samples
SN74LS125ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS125A	Samples
SN74LS125ADBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS125A	Samples
SN74LS125ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS125A	Samples
SN74LS125ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS125A	Samples
SN74LS125ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS125A	Samples
SN74LS125ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS125A	Samples
SN74LS125AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS125AN	Samples
SN74LS125ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS125AN	Samples
SN74LS125ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS125A	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS126AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS126A	Samples
SN74LS126ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS126A	Samples
SN74LS126ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS126A	Samples
SN74LS126ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS126A	Samples
SN74LS126AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS126AN	Samples
SN74LS126ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS126AN	Samples
SN74LS126ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS126A	Samples
SNJ54LS125AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS125AJ	Samples
SNJ54LS125AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS125AW	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54LS125A, SN74LS125A :

- Catalog: [SN74LS125A](#)
- Military: [SN54LS125A](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS125ADBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74LS125ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS125ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LS126ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS126ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS125ADBR	SSOP	DB	14	2000	367.0	367.0	38.0
SN74LS125ADR	SOIC	D	14	2500	367.0	367.0	38.0
SN74LS125ANSR	SO	NS	14	2000	367.0	367.0	38.0
SN74LS126ADR	SOIC	D	14	2500	367.0	367.0	38.0
SN74LS126ANSR	SO	NS	14	2000	367.0	367.0	38.0

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14

J 14

GENERIC PACKAGE VIEW
CDIP - 5.08 mm max height
CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4040083-5/G

J0014A



PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

NOTES:

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

EXAMPLE BOARD LAYOUT

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X





4214771/A 05/2017

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4040047-5/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 -  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211283-3/E 08/12

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - $\triangle D$ The 20 pin end lead shoulder width is a vendor option, either half or full width.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

IMPORTANT NOTICE

Texas Instruments Incorporated (TI) reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete.

TI's published terms of sale for semiconductor products (<http://www.ti.com/sc/docs/stdterms.htm>) apply to the sale of packaged integrated circuit products that TI has qualified and released to market. Additional terms may apply to the use or sale of other types of TI products and services.

Reproduction of significant portions of TI information in TI data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such reproduced documentation. Information of third parties may be subject to additional restrictions. Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyers and others who are developing systems that incorporate TI products (collectively, "Designers") understand and agree that Designers remain responsible for using their independent analysis, evaluation and judgment in designing their applications and that Designers have full and exclusive responsibility to assure the safety of Designers' applications and compliance of their applications (and of all TI products used in or for Designers' applications) with all applicable regulations, laws and other applicable requirements. Designer represents that, with respect to their applications, Designer has all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. Designer agrees that prior to using or distributing any applications that include TI products, Designer will thoroughly test such applications and the functionality of such TI products as used in such applications.

TI's provision of technical, application or other design advice, quality characterization, reliability data or other services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using TI Resources in any way, Designer (individually or, if Designer is acting on behalf of a company, Designer's company) agrees to use any particular TI Resource solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

Designer is authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY DESIGNER AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

Unless TI has explicitly designated an individual product as meeting the requirements of a particular industry standard (e.g., ISO/TS 16949 and ISO 26262), TI is not responsible for any failure to meet such industry standard requirements.

Where TI specifically promotes products as facilitating functional safety or as compliant with industry functional safety standards, such products are intended to help enable customers to design and create their own applications that meet applicable functional safety standards and requirements. Using products in an application does not by itself establish any safety features in the application. Designers must ensure compliance with safety-related requirements and standards applicable to their applications. Designer may not use any TI products in life-critical medical equipment unless authorized officers of the parties have executed a special contract specifically governing such use. Life-critical medical equipment is medical equipment where failure of such equipment would cause serious bodily injury or death (e.g., life support, pacemakers, defibrillators, heart pumps, neurostimulators, and implantables). Such equipment includes, without limitation, all medical devices identified by the U.S. Food and Drug Administration as Class III devices and equivalent classifications outside the U.S.

TI may expressly designate certain products as completing a particular qualification (e.g., Q100, Military Grade, or Enhanced Product). Designers agree that it has the necessary expertise to select the product with the appropriate qualification designation for their applications and that proper product selection is at Designers' own risk. Designers are solely responsible for compliance with all legal and regulatory requirements in connection with such selection.

Designer will fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of Designer's non-compliance with the terms and provisions of this Notice.